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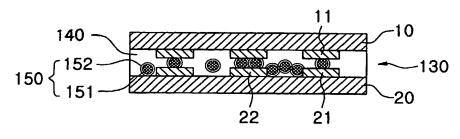
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(54) Title: ANISOTROPIC-ELECTROCONDUCTIVE ADHESIVE, CIRCUIT CONNECTION METHOD AND STRUCTURE USING THE SAME



(57) Abstract: Disclosed is an anisotropic-electroconductive adhesive, which includes insulating adhesive component containing a radical polymerizable compound a polymerization initiator; and a plurality of insulating coated electroconductive particles dispersed in the insulating adhesive component,

insulating coated electroconductive particle having a coating layer made of insulating thermoplastic resin on a surface of an electroconductive particle, wherein a softening point of the insulating thermoplastic resin is lower than an exothermic peak temperature of the insulating adhesive component. The anisotropic-electroconductive adhesive enables rapid curing of the insulating adhesive component at a low temperature and is very useful for making a circuit connection structure since it may prevent a short of circuit without connection failure even when the electroconductive particles are condensed.

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